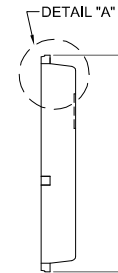
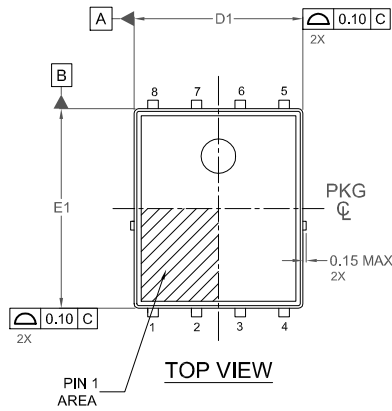

**DFN8 5.1x6.3, 1.27P**  
**CASE 506DW**  
**ISSUE A**

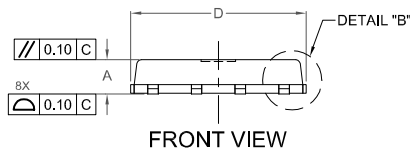
DATE 02 JUL 2021

## NOTES:

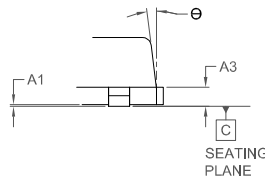
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.
2. CONTROLLING DIMENSION: MILLIMETERS
3. COPLANARITY APPLIES TO THE EXPOSED PADS AS WELL AS THE TERMINALS.
4. DIMENSIONS D1 AND E1 DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.
5. SEATING PLANE IS DEFINED BY THE TERMINALS. "A1" IS DEFINED AS THE DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT ON THE PACKAGE BODY.
6. IT IS RECOMMENDED TO HAVE NO TRACES OR VIAS WITHIN THE KEEP OUT AREA.



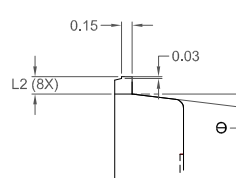
SIDE VIEW



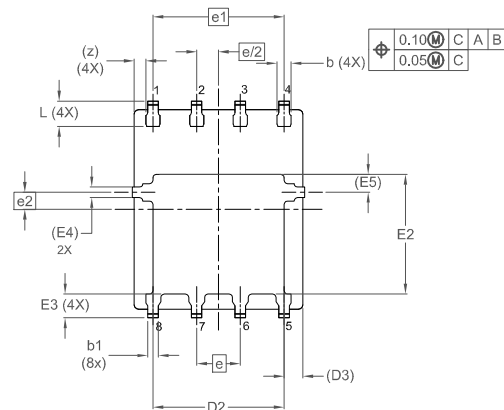
FRONT VIEW



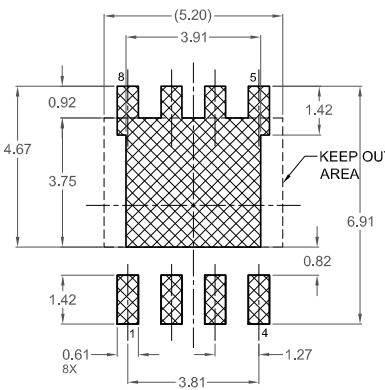
DETAIL "B"



DETAIL "A"



BOTTOM VIEW


**LAND PATTERN**  
**RECOMMENDATION**

\*FOR ADDITIONAL INFORMATION ON OUR PB-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ON SEMICONDUCTOR SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERM/D.

DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	0.90	1.00	1.10
A1	0.00	-	0.05
A3	0.20	0.25	0.30
b	0.36	0.41	0.46
b1	0.26	0.31	0.36
D	4.90	5.00	5.20
D1	4.80	4.90	5.00
D2	3.72	3.82	3.92
D3	0.54 REF		
E	6.20	6.30	6.40
E1	5.70	5.80	5.90
E2	3.38	3.48	3.58
E3	0.59	0.69	0.79
E4	0.30 REF		
E5	0.52 REF		
e	1.27 BSC		
e/2	0.635 BSC		
e1	3.81 BSC		
e2	0.50 BSC		
L	0.64	0.74	0.84
L2	0.15	0.25	0.35
z	0.34 REF		
θ	0°	-	7°

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**DESCRIPTION:** DFN8 5.1x6.3, 1.27P

**PAGE 1 OF 1**

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